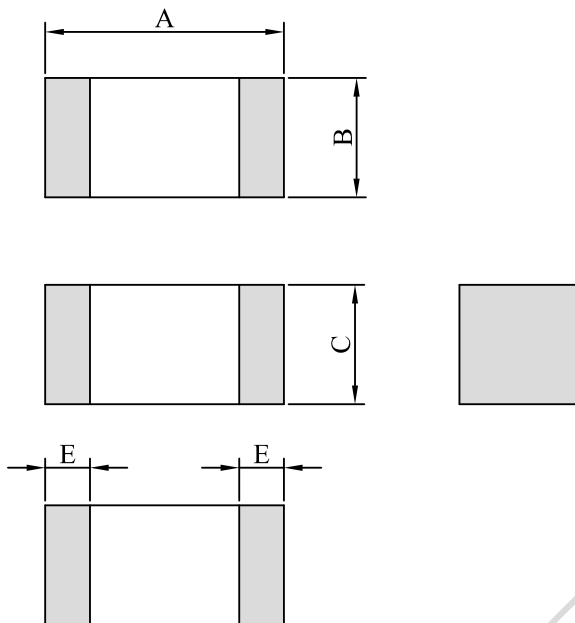


SPECIFICATION

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1608□□□□C□-□□□		
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I . Configuration and dimensions :



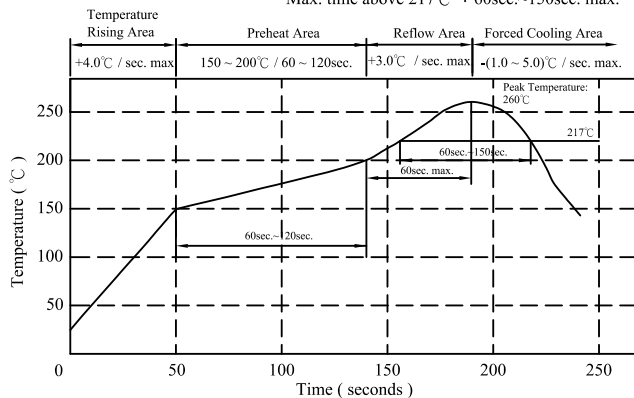
Unit : mm

A	B	C	E
1.60 ±0.2	0.80 ±0.2	0.80 ±0.2	0.30 ±0.2

II . Description :

- a . Body : Ceramic
- b . Inner electrode : Silver
- c . Terminal electrode : Ag / Ni / Sn
- d . Product weight : 4.5 mg (ref.)
- e . Products comply with RoHS' requirements
- f . Halogen free

Peak temp. : 260°C max.
Max. peak temp. - 5°C : 30sec. max.
Max. time above 217°C : 60sec.~150sec. max.



III . General specification :

- a . Operating temp. : -40°C ----+85°C
(Temp. rise included)
- b . Resistance to solder heat : 260°C . 10 sec.

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SPECIFICATION

REF. :

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IV . Electrical characteristics :

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz) L&Q	SRF (MHz) min.	RDC (Ω) max.	IDC (mA) max.
EDP16081N0□CB-□□□	1.000	S,D	8	100M /50mV	10000	0.050	500
EDP16081N2□CB-□□□	1.200	S,D	8	100M /50mV	10000	0.050	500
EDP16081N5□CB-□□□	1.500	S,D	8	100M /50mV	6000	0.100	500
EDP16081N8□CB-□□□	1.800	S,D	8	100M /50mV	6000	0.100	500
EDP16082N0□CB-□□□	2.000	S,D	8	100M /50mV	6000	0.100	500
EDP16082N2□CB-□□□	2.200	S,D	8	100M /50mV	6000	0.100	500
EDP16082N4□CB-□□□	2.400	S,D	8	100M /50mV	6000	0.120	500
EDP16082N7□CB-□□□	2.700	S,D	10	100M /50mV	6000	0.120	500
EDP16083N3□CB-□□□	3.300	S,D	10	100M /50mV	6000	0.150	500
EDP16083N6□CB-□□□	3.600	S,D	10	100M /50mV	6000	0.160	500
EDP16083N9□CB-□□□	3.900	S,D	10	100M /50mV	6000	0.160	500
EDP16084N3□CB-□□□	4.300	S,D	10	100M /50mV	6000	0.180	500
EDP16084N7□CB-□□□	4.700	S,D	10	100M /50mV	6000	0.200	500
EDP16085N1□CB-□□□	5.100	S,D	10	100M /50mV	5500	0.250	500
EDP16085N6□CB-□□□	5.600	S,D	10	100M /50mV	5000	0.250	500
EDP16086N8□CB-□□□	6.800	J,K	10	100M /50mV	5000	0.300	500
EDP16087N5□CB-□□□	7.500	J,K	10	100M /50mV	4500	0.350	500
EDP16088N2□CB-□□□	8.200	J,K	10	100M /50mV	4500	0.350	500
EDP16089N1□CB-□□□	9.100	J,K	10	100M /50mV	3500	0.400	500
EDP160810N□CB-□□□	10.00	J,K	12	100M /50mV	3500	0.400	300
EDP160812N□CB-□□□	12.00	J,K	12	100M /50mV	3000	0.450	300
EDP160815N□CB-□□□	15.00	J,K	12	100M /50mV	2300	0.500	300
EDP160818N□CB-□□□	18.00	J,K	12	100M /50mV	2200	0.550	300
EDP160822N□CB-□□□	22.00	J,K	12	100M /50mV	2000	0.600	300
EDP160824N□CB-□□□	24.00	J,K	12	100M /50mV	2000	0.600	300
EDP160827N□CB-□□□	27.00	J,K	12	100M /50mV	1700	0.650	300
EDP160833N□CB-□□□	33.00	J,K	12	100M /50mV	1500	0.700	300
EDP160836N□CB-□□□	36.00	J,K	12	100M /50mV	1400	0.700	300
EDP160839N□CB-□□□	39.00	J,K	12	100M /50mV	1400	0.700	300
EDP160847N□CB-□□□	47.00	J,K	12	100M /50mV	1200	0.700	300
EDP160856N□CB-□□□	56.00	J,K	12	100M /50mV	1100	0.750	300
EDP160868N□CB-□□□	68.00	J,K	12	100M /50mV	900	0.850	300
EDP160882N□CB-□□□	82.00	J,K	8	100M /50mV	800	1.000	300
EDP1608R10□CB-□□□	100.0	J,K	8	100M /50mV	700	1.200	300
EDP1608R12□CB-□□□	120.0	J,K	8	50M /50mV	600	1.400	200
EDP1608R15□CB-□□□	150.0	J,K	8	50M /50mV	500	1.600	200
EDP1608R18□CB-□□□	180.0	J,K	8	50M /50mV	400	1.900	200
EDP1608R22□CB-□□□	220.0	J,K	8	50M /50mV	350	2.400	200

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SPECIFICATION

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1608□□□□C□-□□□		
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DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz) L&Q	SRF (MHz) min.	RDC (Ω) max.	IDC (mA) max.
EDP1608R27□CB-□□□	270.0	J,K	8	50M /50mV	350	2.600	150
EDP1608R33□CB-□□□	330.0	J,K	8	50M /50mV	350	2.800	150
EDP1608R39□CB-□□□	390.0	J,K	8	50M /50mV	300	3.200	150
EDP1608R43□CB-□□□	430.0	J,K	8	50M /50mV	280	3.400	150
EDP1608R47□CB-□□□	470.0	J,K	8	50M /50mV	250	3.600	150

- 1). Electrical specifications at 25℃
- 2). IDC base on temp. rise 40℃ max.
- 3). □ Represents inductance tolerance : $L_s \leq 6.8\text{nH}$, □ Please select“S/D” level ;
 $L_s > 6.8\text{nH}$, □ Please select “J/K” level ;
- 4). Tolerance :S($\pm 0.3\text{nH}$) 、D($\pm 0.5\text{nH}$) 、J($\pm 5\%$) 、K($\pm 10\%$)

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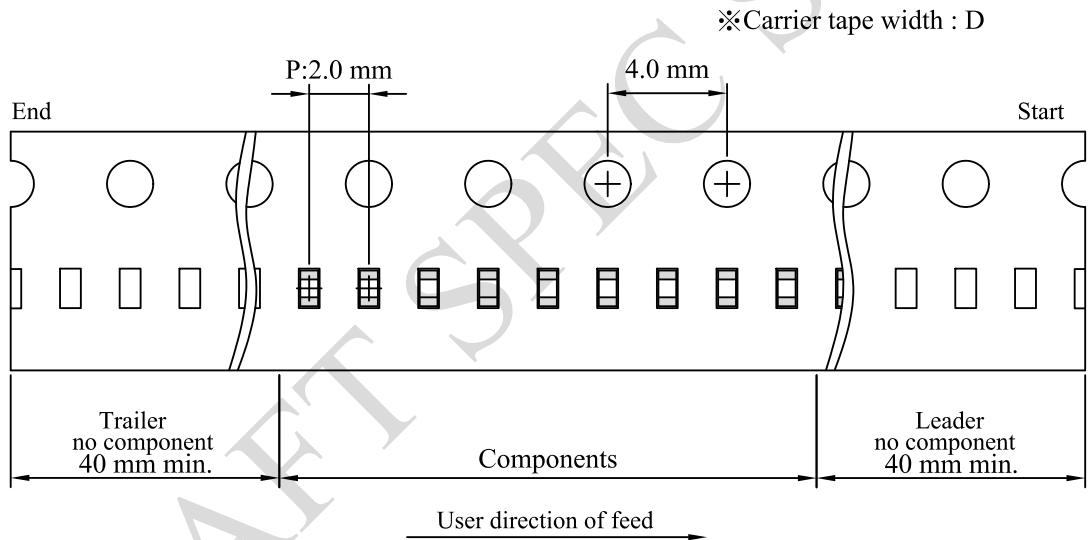
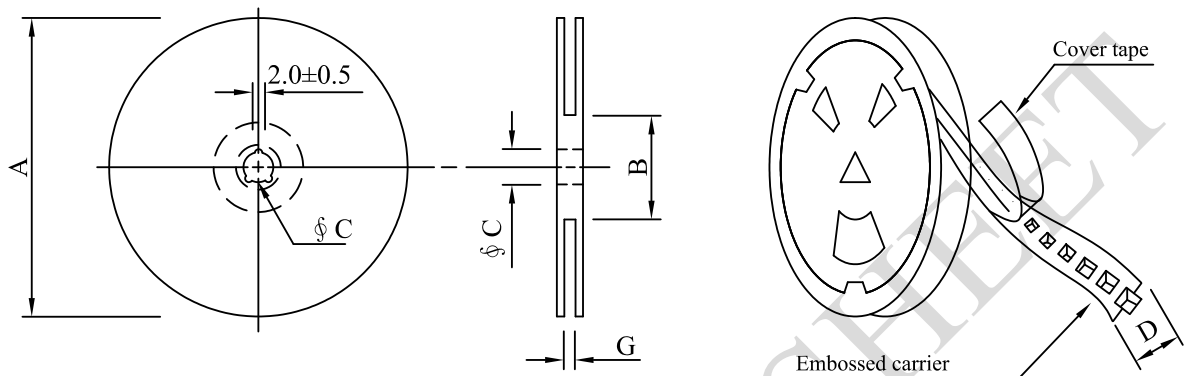
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V . Packaging information :

(1) Configuration



(2) Dimensions

Unit:mm

Style	A	B	C	D	G
07 - 08	178±2.0	57±2.0	12.5±1.5	8	8.0 ^{+1.50} _{-0.00}

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	4,000	110	07 - 08	200,000	6.80	39 x 31 x 39

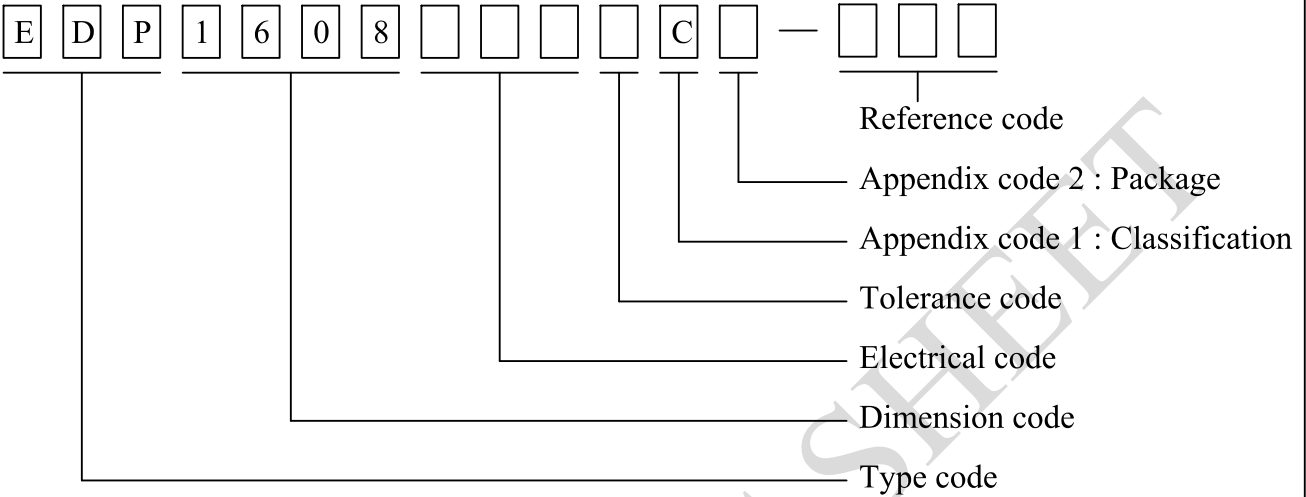
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VI . Drawing number expression :



Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T /R (Reel package)	UCT	Antistatic	Antistatic	4,000 pcs	

SPECIFICATION

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VII . Safety notes :

1. The risks of using the product are highly relevant to the field of application and need to be evaluated by both user and manufacturer. If the product is used for a purpose that directly affects personal safety or will cause significant impact or loss to the society , please be sure to contact us first for confirmation.
產品使用的風險與應用領域有高度相關，若您應用於直接影響人身安全系統或對社會會造成重大影響與損失之相關用途，請務必優先與我們聯繫確認。
2. The storage period is less than 12 months. Ensure to follow the storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 60% RH or less). If the storage time is exceeded the limit, the electrodes might be deteriorate of terminal soldering.
儲存期不超過12個月,務必遵守儲存條件（溫度：5至30°C，濕度：10至60%RH以下）。如果超過了儲存時間，端子電極可能會氧化而影響焊接。
3. Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
不要在有氣體腐蝕等條件的地方使用或存放（鹽，酸，鹼等）。
4. Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
安裝時的焊接條件應在規格範圍內。如果超過要求，可能會發生短路，性能下降或壽命縮短。
5. When using, it should try to avoid excessive mechanical impact on the product, such as collision / drop ... and other reasons.
使用時，應盡量避免產品受到過度機械衝擊，如碰撞/掉落...等原因。
6. When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.
將已安裝新片的電路板組裝到裝置時，請注意應盡量避免電路板受到組裝變形...等，導致產品受到應力。
7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
產品會因通電而自我發熱(溫度上升)，因此在熱影響設計方面，需保留適當公差。
8. Do not expose the products to magnets or magnetic fields.
請勿將產品暴露於磁鐵或是磁場中。
9. If you would like to use this products to performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property, or if you have special requirements exceeding the range or conditions set forth in the each catalog, please contact us.
如果您希望將此產品用於性能和/或質量要求更嚴格的安全性或可靠性，或其失敗、故障或麻煩可能對社會、個人或財產造成嚴重損害，或者您有特殊情況要求超出目錄中規定的範圍或條件，請與我們聯繫。